



Typical Applications

For use in low voltage high frequency inverters, freewheeling, DC/DC converters, automotive and polarity protection applications.

Mechanical Date

- **Package:** SOD-323HE
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free
- **Terminals:** Tin plated leads, solderable

			FM115EQ
Device marking code			115
Repetitive peak reverse voltage	V_{RRM}	V	150
Maximum RMS current	I_{RMS}	A	105
			150
			1.0
			30
@60Hz half-sine wave, 1 cycle, $T_J=25$	I_{FSM}	A	
Voltage rate of change (rated V_R)	dV/dt	V/ μ s	10000
Storage temperature	T_{stg}		-55 ~+175
Junction temperature	T_J		-55 ~+175

■Electrical Characteristics ($T_A=25$ Unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS		TYP	MAXEST CC ? ^e	
Instantaneous forward voltage	V _F	I _F =1A	T _J =25	0.8	0.9	V
			T _J =125	-	0.7	
Reverse current	I _R	Rated V _R	T _J =25	-	1	uA
			T _J =125	-	50	uA
Typical junction capacitance	C _J	V _R =4V,f=1MHz		25	-	pF



FM115EQ

■ Thermal Characteristics ($T_a=25$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	FM115EQ
Thermal resistance	$R_{\theta J-A}$	/W	260 ¹
	$R_{\theta J-L}$		70 ¹
	$R_{\theta J-SP}$		10 ²

Note:

- (1) Thermal resistance between junction and ambient and between junction and lead mounted on P.C.B without copper pad areas.
- (2) Thermal resistance between junction and cathode tab solder point.

■ Characteristics(Typical)

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE
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■ Marking Information

■ Outline Dimensions

SOD-323HE		
Dim	Millimeters	
	Min	Max
A	1.20	1.40
B	2.10	2.30
C	2.30	2.70
D	0.90	1.00
E1	0.55	0.75

■ Suggested pad layout

